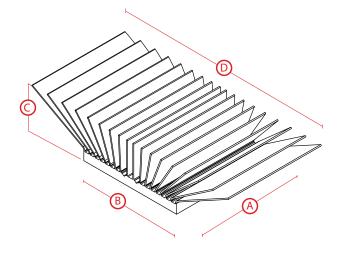


Ultra High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-52150P-C2-R0

Features & Benefits

- » maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- » Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks





*Image above is for illustration purposes only.

Thermal Performance

AIR VELOCITY			THERMAL RESISTANCE		
T/MIN	Μ	I/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1	.0	8.7	7.1	
300	1	.5	7.2		
400	2	.0	6.3		
500	2	.5	5.7		
600	3	.0	5.2		
700	3	.5	4.9		
800	4	.0	4.6		
	T/MIN 200 300 400 500 600 700	T/MIN M 200 1 300 1 400 2 500 2 600 3 700 3	T/MIN M/S 200 1.0 300 1.5 400 2.0 500 2.5 600 3.0 700 3.5	T/MINM/S°C/W (UNDUCTED FLOW)2001.08.73001.57.24002.06.35002.55.76003.05.27003.54.9	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
15 mm	15 mm	17.5 mm	30.6 mm	SAINT-GOBAIN C675	BLUE-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

2) Thermal performance data are provided for reference only. Actual performance may vary

by application.ATS reserves the right to update or change its products without notice to improve the

design or performance.4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).